

Draft **ETSI EN 301 605** V1.1.1 (2013-01)



**Environmental Engineering (EE);
Earthing and bonding of 400 VDC data and telecom
(ICT) equipment**

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Foreword

This draft European Standard (EN) has been produced by ETSI Technical Committee Environmental Engineering (EE), and is now submitted for the combined Public Enquiry and Vote phase of the ETSI standards EN Approval Procedure.

The present document has been produced within the framework of the following considerations:

- a) Datacommunications and Telecommunications (ICT) equipment is generally installed in data and telecom centres and held in racks, cabinets or other mechanical structures;
- b) the existing ITU-T and CCIR Recommendations and CENELEC standards in such matters do not ensure the required standardization at the equipment level;
- c) network operators and equipment providers agreed to standardize on a bonding configuration that facilitates:
 - compliance with functional requirements including Electromagnetic Compatibility (EMC) aspects of emission and immunity;
 - compatible building and equipment provisions;
 - installation of new data and telecom centres as well as expansion or replacement of installations in existing data and telecom centres with equipment coming from different suppliers;
 - a structured installation practice;
 - simple maintenance rules;
 - contracting on a common basis;
 - cost effectiveness in development, manufacturing, installation and operation.

Proposed national transposition dates

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